



Switching Diode

Power Dissipation - 400 mWatts

Features

- Silicon epitaxial planar diode
- ●SMD chip pattern, available in various dimension included 0805
- Leadfree and RoHS compliance components
- For AC switching input as rectified circuit and high reverse voltage location

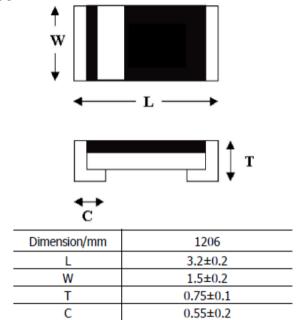
Mechanical Data

• Size: 1206

Weight: approx. 10mg

Marking: Cathode terminal

1206



Package Outline Dimensions in Millimeters

Maximum Ratings and Electrical Characteristics

Rating at 25℃ ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristics	Symbol	Value	Unit
Forward Power Dissipation	Ptot	400	mW
Power derating above 25 ℃	Pioi	3.2	mW/ ℃
Junction Temperature	Tj	150	°C
Thermal Resistance Junction to Ambient air	Reja	375	,C\M
Operating& Storage Temperature range	Tstg	-55 to +150	$^{\circ}$
Repetitive Peak Reverse Voltage	VRRM	100	V
Average rectified current sin half wave rectification with resistive load	lf(AV)	150	mA
Repetitive Peak Forward Current at Tamb=25°C	IFRM	300	mA
Non-Repetitive Surge Forward Current at t<1s and Tj=25℃	IFSM	500	mΛ
at t≦8.3ms and Tj=25℃		1000	mA
Forward Voltage at IF=10mA	VF	1.0 MAX	V
at I =100mA		1.25 MAX	V
Leakage Current at VR=20V	IR —	0.025 MAX	uA
Leakage Current at V =80V		0.5 MAX	uA
Capacitance at VR=0V, f=1MHz	Ctot	4 MAX	pF
Reverse Recovery Time at IF =IR=10mA,RL=100Ω	trr	4 MAX	ns

Notes: Valid provided that electrodes are kept at ambient temperature.

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Figure 3. Forward Current Derating

500
400
300
100
0 20 40 60 80 100 120 140 160 180 200
Tamb-Ambient Temperature/oC

Figure 4. Reverse Voltage De-rating

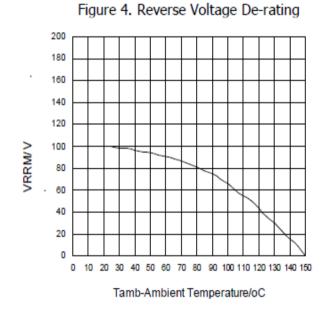
200
180
160
140
120
80
80
40
20
0 10 20 30 40 50 60 70 80 90 100 110 120 130 140 150

Tamb-Ambient Temperature/oC

400 300 100 0 20 40 60 80 100 120 140 160 180 200

Tamb-Ambient Temperature/oC

Figure 3. Forward Current Derating



The curve above is for reference only.

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